

SOT868-1

plastic thin fine-pitch ball grid array package; 240 balls; body
12 x 12 x 0.7 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA240
Package type industry code	TFBGA240
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-9-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.15	1.15	mm
A ₂	package height	0.6	-	0.7	0.8	mm
n ₂	actual quantity of termination	-	-	240	-	



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2. Package outline

TFBGA240: plastic thin fine-pitch ball grid array package; 240 balls; body 12 x 12 x 0.7 mm SOT868-1

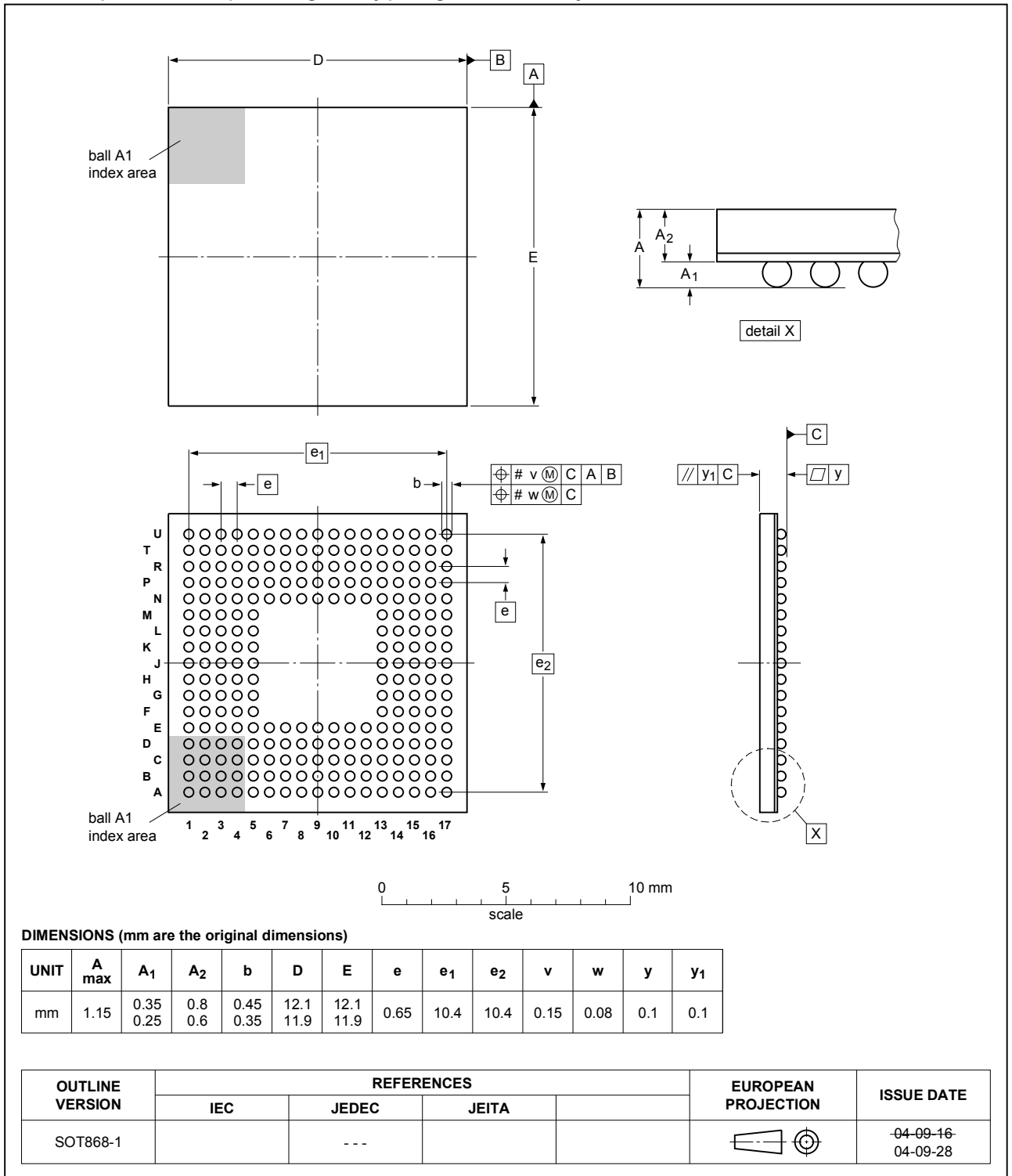


Fig. 1. Package outline TFBGA240 (SOT868-1)

3. Soldering

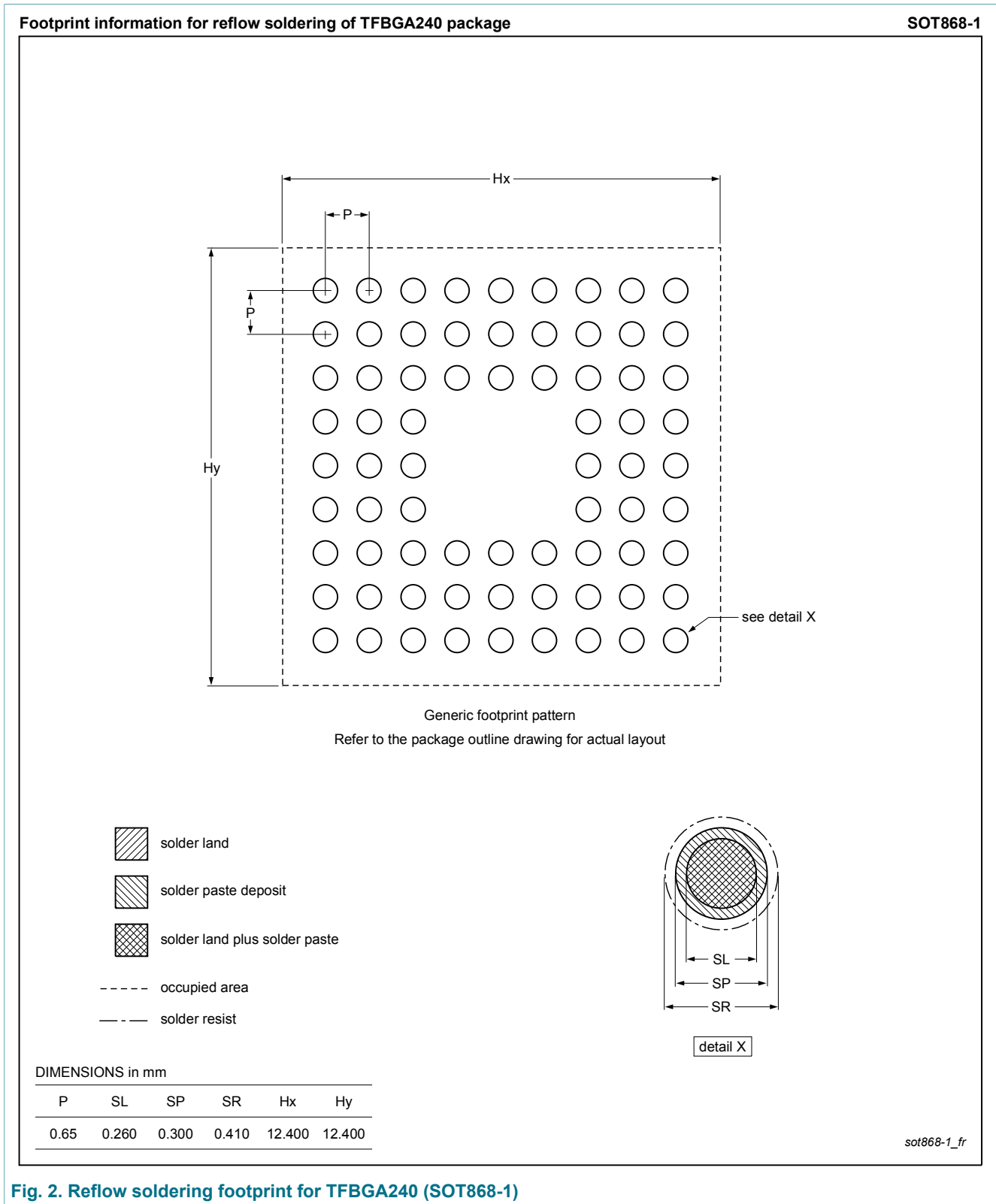


Fig. 2. Reflow soldering footprint for TFBGA240 (SOT868-1)

4. Legal information

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